



MICROSPIN
TECHNOLOGIES

PRODUCT DATASHEET
WWW.MICROSPIN.EU

Prepatterned Chips

PRICE
from **€100**

SILICON-BASED PREPATTERNS WITH GOLDEN ELECTRODE SYSTEM
FOR CLEANROOM-FREE SAMPLE FABRICATION

2- / 4-point
ELECTRODE SYSTEM

Ti/Au 50 nm
CONTACT MATERIAL

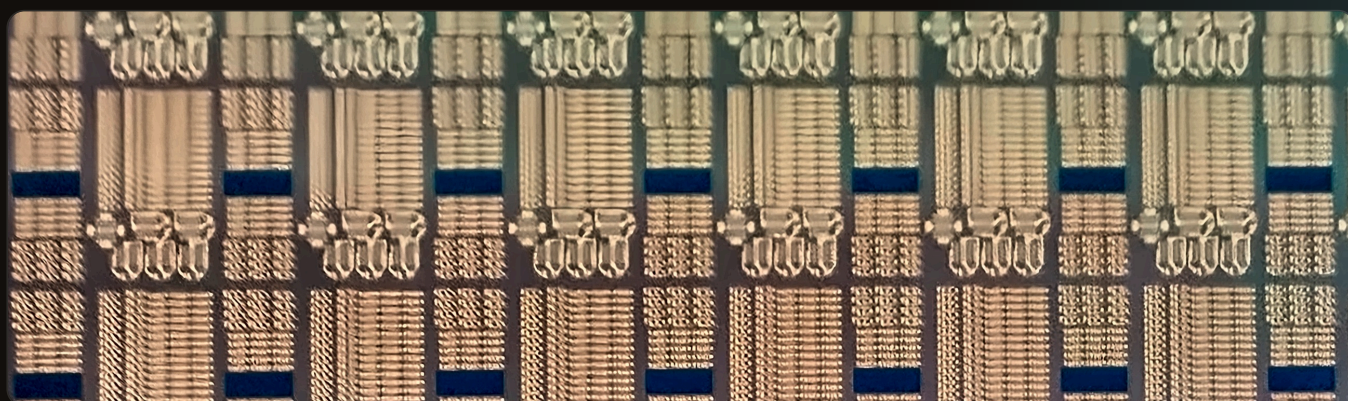
100 mA
MAX. CURRENT

100 × 100 μm
CONTACT PAD SIZE

PRODUCT OVERVIEW

Silicon-based prepatterns with a golden electrode system enable cleanroom-free sample fabrication for fast electronic transport testing. Tens of prepatterned prototype devices for various types of testing are available in a few minutes.

To make a working prototype, **conventional deposition** (magnetron sputtering, evaporation, pulsed laser deposition) is sufficient, followed by a fast lift-off process.



PREPATTERNED Si/SiO₂ WAFER WITH TI/AU ELECTRODE SYSTEM

TECHNICAL SPECIFICATIONS

PARAMETER	SPECIFICATION / RANGE
Electrode system	Two- and four-point system
Contact material	50 nm-thick Ti/Au
Current range	Up to 100 mA
Contact pad size	100 × 100 μm
Substrate	High-resistive Si/SiO₂

STANDARD PATTERNS

- **Hall bars** with two- and four-point electrode system
- **Longitudinal and transversal** resistance measurement
- **Compatible layout** enabling fast interfacing with ROTA microprobes



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Advanced measurement systems for spintronic devices